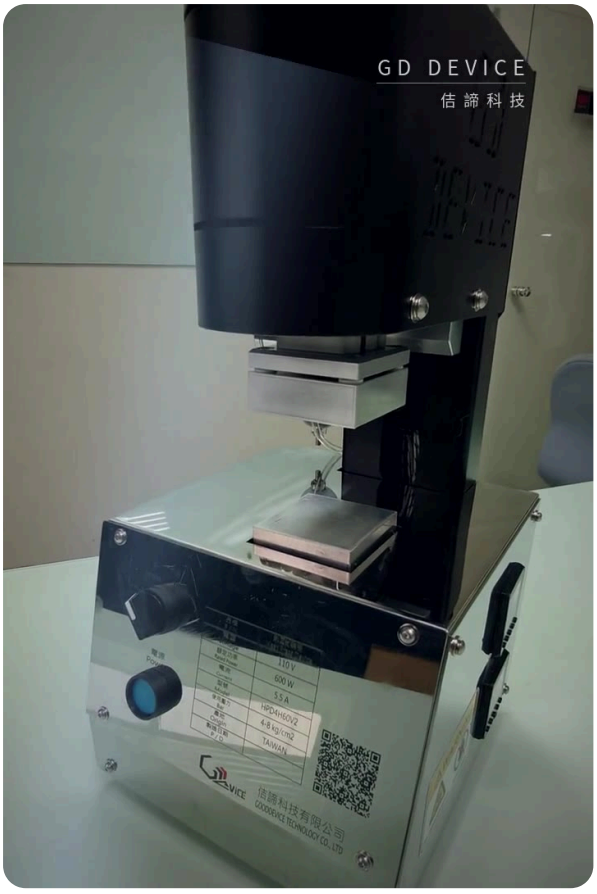
桌上型精密熱壓封裝機
操作手冊

Benchtop Precision Hot Press Bonding & Sealing Machine — Operation Manual



本手冊依操作示範影片整理，說明機台從接線、設定溫度到壓合的 6 個基本步驟。首次使用前請完整閱讀，並遵守最後一頁的安全注意事項。

This manual follows the operation demo video and covers the six basic steps from connection and temperature setting to pressing. Please read it fully, including the safety notes, before first use.

上下雙區獨立控溫　4 分鐘升溫至 200°C　緩衝下壓・壓面自動調平

主要規格

SPECIFICATIONS

溫度範圍 Temperature	常溫～250°C Ambient to 250°C
壓力 Pressure	1–5 kgf/cm²
有效封裝面積 Sealing area	60 × 60 mm／120 × 120 mm
電源 Power	AC110V 50/60Hz
氣源 Air supply	5–7 Bar
加熱方式 Heating	上、下壓板雙區獨立控溫 Independent upper / lower zones

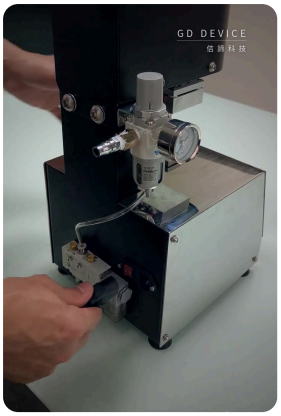
溫度、壓力與封裝面積可依製程客製。 Specifications can be customized to your process.

適用應用 Applications　導電玻璃與面板類封裝、DSSC 染料敏化太陽能電池封裝、LCD 玻璃面板貼合、PCB 與電子元件壓合、實驗室研發打樣

Conductive glass & panel packaging, DSSC solar cell sealing, LCD panel bonding, PCB & component lamination, lab R&D sampling

操作步驟

OPERATING STEPS



STEP 01 / 06

接上電源與氣源

CONNECT POWER & AIR

將電源線插入機台背面的電源插座，再把氣管接上背面調壓閥的快速接頭。

Plug the power cord into the rear inlet, then connect the air hose to the quick coupler on the rear pressure regulator.



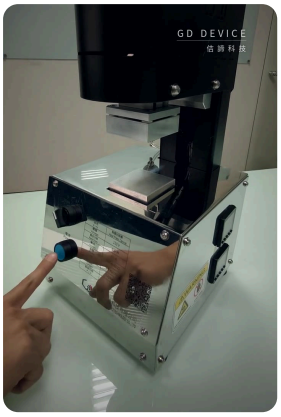
STEP 02 / 06

確認氣壓 5–7 Bar

CHECK AIR PRESSURE

看調壓閥上的壓力錶，確認氣壓在 5–7 Bar 之間；不足時請調整氣源或調壓閥。

Read the regulator gauge and make sure the supply is between 5 and 7 bar; adjust the regulator if needed.



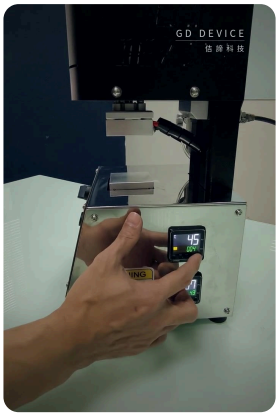
STEP 03 / 06

開啟電源

POWER ON

按下機台正面的電源按鈕，溫控器亮起即完成開機。

Press the power button on the front panel. The temperature controllers light up when the machine is on.



STEP 04 / 06

上下雙區，獨立控溫

INDEPENDENT DUAL-ZONE HEATING

側面兩組溫控器分別控制上、下壓板。依材料需求各自設定目標溫度（上方為現在溫度，下方為設定溫度）。

The two controllers on the side set the upper and lower platens separately. Set each target temperature for your material (top figure: actual, bottom figure: set point).



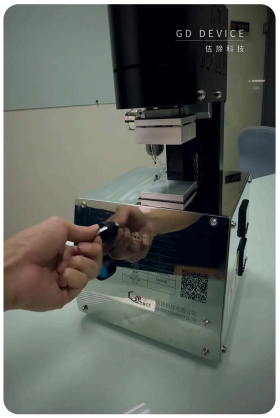
STEP 05 / 06

4 分鐘內升溫至 200°C

200°C IN UNDER 4 MINUTES

開始加熱後約 4 分鐘內即可到達 200°C。請等實際溫度到達設定值並穩定後再開始壓合。

The platens reach 200°C in under 4 minutes. Wait until the actual temperature reaches and holds the set point before pressing.



STEP 06 / 06

一鍵啟動壓合

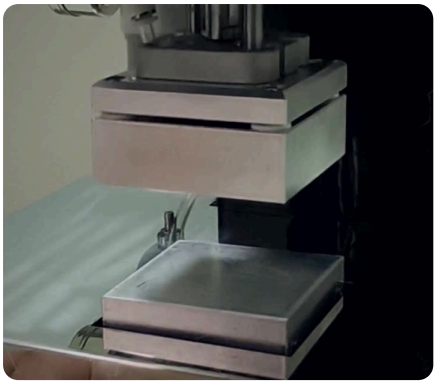
ONE-TOUCH PRESSING

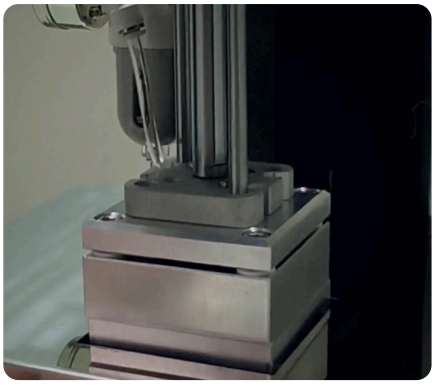
將工件放在下壓板上，按一下機台正面的「啟動」按鈕，上壓板即自動下壓壓合；完成並升起壓板後再取出工件。

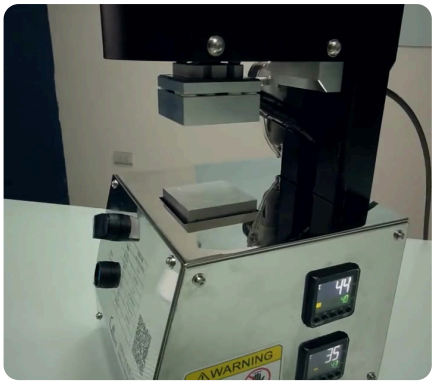
Place the workpiece on the lower platen and press the START button on the front panel once. The upper platen lowers and bonds automatically. Remove the part after bonding, once the platen has risen.

產品特點：緩衝下壓，壓面自動調平

KEY FEATURE: CUSHIONED PRESS, SELF-LEVELING PLATEN







上壓板以緩衝方式下壓，接觸工件時壓面會自動調平，讓整個封裝面受力平均，不易壓傷玻璃或產生偏壓。特別適合導電玻璃、面板類等需要均勻壓合的封裝製程。

The upper platen comes down with a cushioned stroke and levels itself on contact, spreading pressure evenly across the sealing area so glass is not cracked or pressed unevenly — ideal for conductive glass and panel packaging.

安全注意事項

SAFETY NOTES

- 加熱中與停機後一段時間內，壓板與周圍金屬件溫度很高，請勿直接觸碰（機台上貼有警示標籤）。
  Platens and nearby metal stay hot during and after heating. Do not touch (see warning label).
- 壓板下降時，手指與工具請勿伸入上下壓板之間。
  Keep fingers and tools out from between the platens while lowering.
- 請使用 AC110V 電源並確實接地；氣源維持 5–7 Bar 的乾淨乾燥空氣。
  Use a grounded AC110V supply and clean, dry air at 5–7 bar.
- 建議使用完畢後，先讓壓板降溫，再關閉電源與氣源。
  After use, let the platens cool before switching off power and air.
- 如有異常聲響、溫度無法上升或壓力異常，請停止使用並與我們聯絡。
  Stop using the machine and contact us if you notice abnormal noise, heating or pressure.

操作示範影片 Video demo　請至產品頁觀看完整操作影片：
gddevice.com/services/precision-hot-press-bonding-sealing-machine/

聯絡我們

CONTACT

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